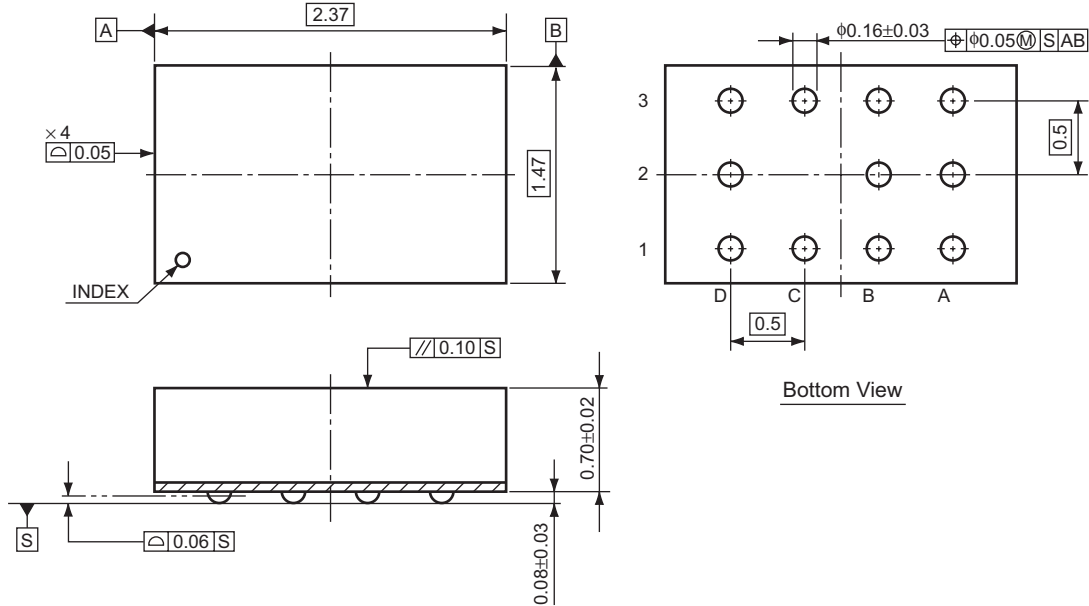


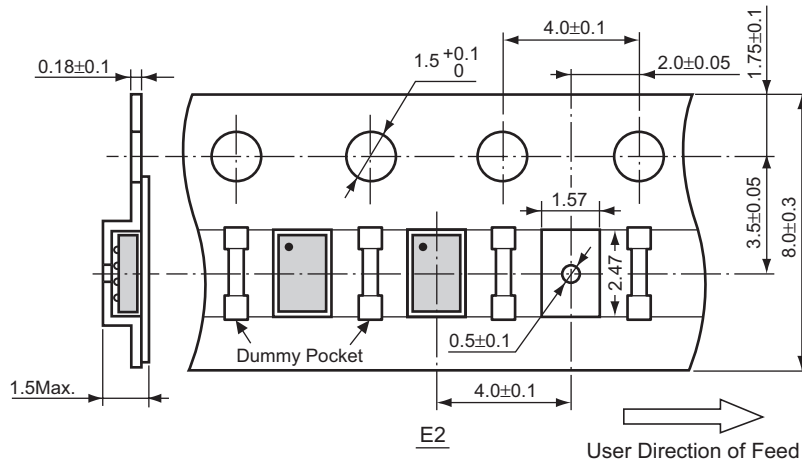
• WLCSP-11-P2

Unit: mm

PACKAGE DIMENSIONS

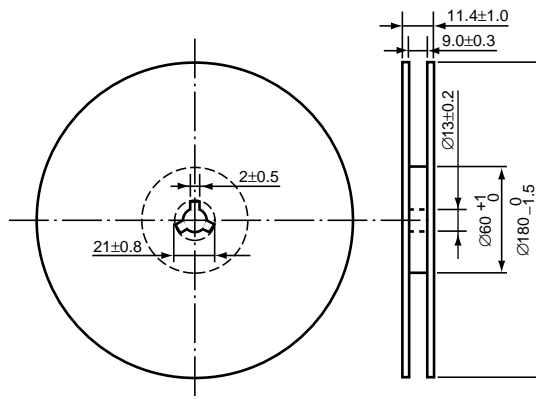


TAPING SPECIFICATION



TAPING REEL DIMENSIONS REUSE REEL (EIAJ-RRM-08Bc)

(1reel=4000pcs)



POWER DISSIPATION (WLCSP-11-P2)

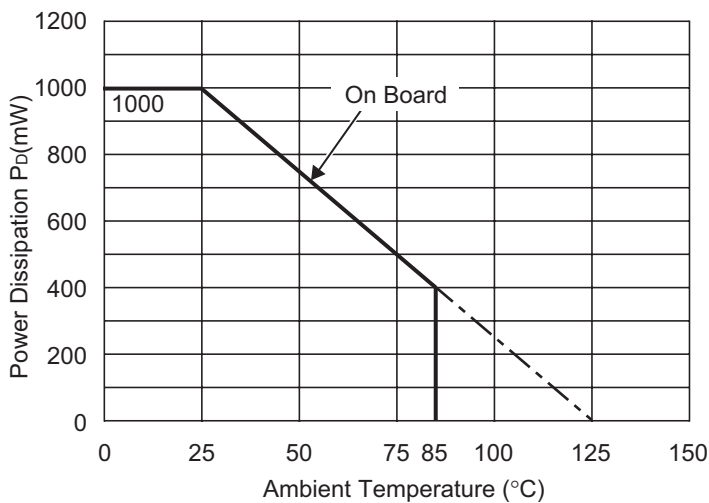
This specification is at mounted on board. Power Dissipation (P_D) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

Measurement Conditions

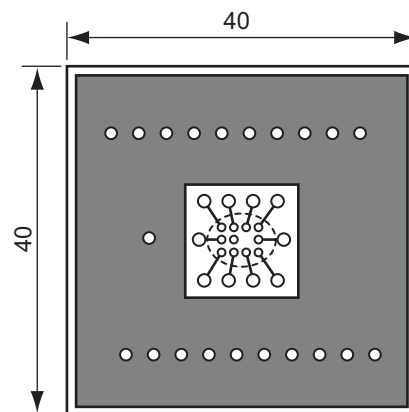
	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)
Board Dimensions	40mm × 40mm × 1.6mm
Copper Ratio	Top side : Approx. 80%, Back side : Approx. 90%
Through-hole	φ0.6mm × 31pcs

Measurement Result ($T_{opt}=25^{\circ}C$, $T_{jmax}=125^{\circ}C$)

	Standard Land Pattern
Power Dissipation	1000mW
Thermal Resistance	$\theta_{ja}=(125-25^{\circ}C)/1W=100^{\circ}C/W$
Thermal Resistance	$\theta_{jc}=7^{\circ}C/W$



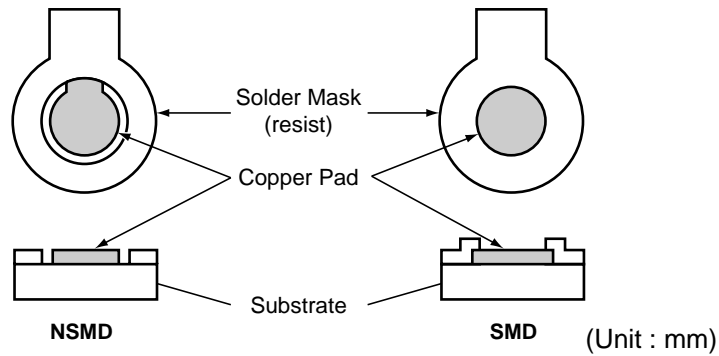
Power Dissipation



Measurement Board Pattern

○ IC Mount Area Unit : mm

RECOMMENDED LAND PATTERN



NSMD and SMD Pad Definition

Pad definition	Copper Pad	Solder Mask Opening
NSMD (Non-Solder Mask defined)	0.20mm	Min. 0.30mm
SMD (Solder Mask defined)	Min. 0.30mm	0.20mm

- * Pad layout and size can be modified by customers material, equipment, method.
- * Please adjust pad layout according to your conditions.
- * Recommended Stencil Aperture Size...ø0.3mm
- * Since lead free WL-CSP components are not compatible with the tin/lead solder process, you shall not mount lead free WL-CSP components using the tin/lead solder paste.